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Interested committees:

Title: BS EN IEC 63287-4 Semiconductor devices - Guidelines for reliability qualification plans

Part 4: Early failure assessment

Please notify the secretary if you are aware of any keywords that might assist in classifying or identifying the standard or if the content of this standard

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For international standards, comments will be reviewed by the relevant UK national committee before sending the consensus UK vote and comments to the international committee, which will then decide appropriate action. If the international standard is approved, it is usual for the text to be published as a British Standard.

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UK Vote

Please indicate whether you consider the UK should submit a negative (with supporting technical reasons) or positive vote on this draft. Please indicate if you are aware of any reason why this draft standard should not be published as a British Standard.

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Template for comments and secretariat observations

Date: xx/xx/20xx	Document: ISO/DIS xxxx
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1	2	(3)	4	5	(6)	7
MB	Clause No./ Subclause No./Annex (e.g. 3.1)	Paragraph/Figure/ Table/Note	Type of comment	Commend (justification for change) by the MB	Proposed change by the MB	Secretariat observations on each comment submitted
	3.1	Definition 1	ed	Definition is ambiguous and needs clarifying.	Amend to read '...so that the mains connector to which no connection...'	
	6.4	Paragraph 2	te	The use of the UV photometer as an alternative cannot be supported as serious problems have been encountered in its use in the UK.	Delete reference to UV photometer.	



47/2892/CD

COMMITTEE DRAFT (CD)

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CLOSING DATE FOR COMMENTS:

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SUPERSEDES DOCUMENTS:

47/2835/NP, 47/2855/RVN

IEC TC 47 : SEMICONDUCTOR DEVICES

SECRETARIAT:

Korea, Republic of

SECRETARY:

Mr Cheolung Cha

OF INTEREST TO THE FOLLOWING COMMITTEES:

HORIZONTAL FUNCTION(S):

ASPECTS CONCERNED:

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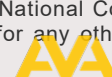
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TITLE:

Semiconductor devices - Guidelines for reliability qualification plans - Part 4: Early failure assessment

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SEMICONDUCTOR DEVICES –

GUIDELINES FOR RELIABILITY QUALIFICATION PLANS –

Part 4: Early failure assessment

FOREWORD

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IEC 63287 Part 4 has been prepared by IEC technical committee 47: Semiconductor devices. It is an International Standard.

The text of this International Standard is based on the following documents:

Draft	Report on voting
47/XX/FDIS	47/XX/RVD

Full information on the voting for its approval can be found in the report on voting indicated in the above table.

The language used for the development of this International Standard is English.